Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S12 7	116	(wafer or carrier) same (diced or dicing or singulat\$4 or separat\$4) same (wire or wired or wiring or connection) same (test\$4 near pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/25 17:55
S12 8	76	S127 and ((@ad<"20020122") or (@rlad<"20020122"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/25 18:33
S12 9	27	dicing with (wire or wired or wiring) with (test\$4 near4 pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/25 18:28
S13 0	240	(wire or wired or wiring or (conductive near path) or connection) same (bond near pad) with (test\$4 near pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/25 18:32
S13 1	10	(257/E21.523).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/07/25 18:33
S13 2	1735	(257/E21.521).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/07/25 18:33
S13 3	21	S132 and (test\$4 near pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/25 18:33
S13 4	20	S133 and ((@ad<"20020122") or (@rlad<"20020122"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/25 18:34

S13	2	("5294776"   "5969538").PN.	US-PGPUB;	OR	ON	2007/07/25 18:34
5		( 3294770   3909330 J.FN.	USPAT; USOCR	OK	ON	2007/07/25 18.54
S13 7	24450	Blum	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/25 18:43
S13 8	19	S137 and (test near pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/25 18:43
S13 9	2	("5059899"   "5981971").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/07/25 18:48
S14 0	62	(active or inactive) same (die or chip or IC or dice or element or component or (integrated near circuit)) same (test\$4 near pad) same (wire or wired or wiring or connection)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/26 10:44
S14 1	16	(test\$4 near pad) near8 active same die	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/26 10:46
S14 2	1735	(257/E21.521).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/07/26 10:46
S14 3	21	S142 and (test\$4 near pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/26 10:48
S14 4	12	(257/E21.524).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/07/26 10:49

S14 5		active same inactive same die same (bond\$4 near pad) same (test\$4 near pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/26 10:50
S14 6	4	active same inactive same (bond\$4 near pad) same (test\$4 near pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/26 10:51
S14 7	25	active same inactive same (test\$4 near pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/26 10:55
S14 8	21	S147 not S146	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/26 10:51
S14 9	40865	active same inactive same (die or chip or element or IC or (integrated near circuit) or device or component)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/26 10:56
S15 0	138	S149 and (test\$4 near pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/26 11:25
S15 1	23	(top near view) near8 (active same inactive)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/26 11:25
S15 2	16198273	(chip or die or IC or (integrated near circuit) or device or component or element)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/26 11:25

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S15 3	10	S151 and ((@ad<"20020122") or (@rlad<"20020122"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/26 11:27
S15 4	5274	S152 same (test\$4 near pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/26 11:41
S15 5	10	(active or inactive) near8 die same (wire or wired or wiring or connection) same (test\$4 near pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 10:11
S15 6	244	(active near8 inactive) near8 die	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 10:12
S15 7	1	S156 same (test\$4 near pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 10:12
S15 8	436	(bond\$4 near pad) near8 (test\$4 near pad) same (die or chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 10:13
S15 9	311	S158 and ((@ad<"20020122") or (@rlad<"20020122"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 11:28
S16 0	1	(test\$4 near pad) near8 (inactive near4 portion) same (die or chip or IC or (integrated near circuit) or device or component or element)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 10:32

S16 1	554	(test\$4 near pad) near8 (side or peripheral or periphery or inactive or outside) same (die or chip or IC or (integrated near circuit) or device or component or element)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 10:33
S16 2	391	S161 and ((@ad<"20020122") or (@rlad<"20020122"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 11:06
S16 3	2	("6611053").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/07/27 11:26
S16 4	37836	Micron.as.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 11:27
S16 5	416	Lunde.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 11:27
S16 6	38227	S164 or S165	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 11:27
S16 7	422	S166 and (test\$4 near pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 11:28
S16 8	55	S167 and active and inactive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 11:28

S16 9	52	S168 and ((@ad<"20020122") or (@rlad<"20020122"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 11:50
S17 0	5	(test\$4 near pad) same (bond\$4 near pad) same inactive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 15:25